

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

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Listing of the Claims

1. (currently amended) ~~An electronic~~ A circuitry component comprising:
a semiconductor substrate;
10 a metallization structure over said semiconductor substrate;
a passivation layer over said metallization structure, wherein an opening in said passivation layer exposes a top surface of said metallization structure; and
a patterned circuit layer connected to said top surface, wherein said patterned circuit layer comprises a first portion ~~having used to have~~ used to have a bump formed thereover
15 and a second portion used to be tested thereto.
2. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said patterned circuit layer comprises gold.
- 20 3. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said patterned circuit layer comprises a gold layer having a thickness greater than 1 micron.
4. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said
25 patterned circuit layer comprises copper.
5. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said patterned circuit layer comprises nickel.
- 30 6. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said patterned circuit layer comprises a copper layer and a gold layer, said gold layer being over said copper layer.

7. (currently amended) The ~~electronic~~ circuitry component of Claim 6, wherein said patterned circuit layer further comprises a nickel layer between said copper layer and said gold layer.

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8. (currently amended) The ~~electronic~~ circuitry component of Claim 1 further comprising a polymer layer over said passivation layer, wherein said patterned circuit layer is over said polymer layer.

10 9. (currently amended) The ~~electronic~~ circuitry component of Claim 8, wherein said polymer layer comprises polyimide.

10. (currently amended) The ~~chip structure~~ circuitry of Claim 1 further comprising a polymer layer on said patterned circuit layer, an opening in said polymer layer
15 exposing said first portion.

11. (currently amended) The ~~electronic~~ circuitry component of Claim 10, wherein said polymer layer comprises polyimide.

20 Claim 12 (canceled)

13. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said patterned circuit layer comprising a metal trace connecting said first and second portions.

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Claim 14 (canceled)

15. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said passivation layer comprises a topmost nitride layer of said electronic component.

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16. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said passivation layer has a thickness greater than 0.35 μm .

17. (currently amended) The ~~electronic~~ circuitry component of Claim 1 further comprising a bump on said first portion.

5 18. (currently amended) The ~~electronic~~ circuitry component of Claim 17 further comprising a nickel layer between said bump and said first portion.

19. (currently amended) The ~~electronic~~ circuitry component of Claim 17, wherein said bump comprises solder.

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20. (currently amended) The ~~electronic~~ circuitry component of Claim 17 further comprising a copper layer between said bump and said first portion.

15 21. (currently amended) The ~~electronic~~ circuitry component of Claim 17, wherein said bump comprises a lead-free alloy.

Claim 22 (canceled)

20 23. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein said patterned circuit layer comprises a third portion used to be wirebonded thereto.

24. (currently amended) The ~~electronic~~ circuitry component of Claim 23, wherein said patterned circuit layer comprises a metal trace connecting said second and third portions.

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25. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein the pitch between said first and second portions is less than 300 μm .

30 26. (currently amended) The ~~electronic~~ circuitry component of Claim 1, wherein the pitch between said first and second portions is less than 1 millimeter.

27. (currently amended) ~~An electronic~~ A circuitry component comprising:

a semiconductor substrate;

a metallization structure over said semiconductor substrate;

a passivation layer over said metallization structure, wherein an opening in said passivation layer exposes a top surface of said metallization structure; and

- 5 a patterned circuit layer connected to said top surface, wherein said patterned circuit layer comprises a first metal layer and a second metal layer over said first metal layer, wherein said second metal layer has a first portion used to have having a bump formed thereover and a second portion used to be wirebonded thereto.

- 10 28. (currently amended) The ~~electronic~~ circuitry component of Claim 27, wherein said ~~patterned circuit~~ second metal layer comprises gold.

29. (currently amended) The ~~electronic~~ circuitry component of Claim 27, wherein said ~~patterned circuit~~ second metal layer comprises copper.

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30. (currently amended) The ~~electronic~~ circuitry component of Claim 27 further comprising a polymer layer over said passivation layer, wherein said patterned circuit layer is over said polymer layer.

- 20 31. (currently amended) The ~~electronic~~ circuitry component of Claim 30, wherein said polymer layer comprises polyimide.

32. (currently amended) The ~~electronic~~ circuitry component of Claim 27 comprising a polymer layer on said patterned circuit layer, an opening in said polymer layer
25 exposing said first portion.

33. (currently amended) The ~~electronic~~ circuitry component of Claim 32, wherein said polymer layer comprises polyimide.

- 30 34. (currently amended) The ~~electronic~~ circuitry component of Claim 27, wherein said patterned circuit layer comprises a metal trace connecting said first and second portions.

35. (currently amended) The ~~electronic~~ circuitry component of Claim 27, wherein said patterned circuit layer comprises a third portion used to be tested thereto.

5 Claim 36 (canceled)

37. (currently amended) The ~~electronic~~ circuitry component of Claim 35, wherein the pitch between said first and second portions is less than 300 μm .

10 38. (currently amended) The ~~electronic~~ circuitry component of Claim 27, wherein said passivation layer has a thickness greater than 0.35 μm .

39. (currently amended) The ~~electronic~~ circuitry component of Claim 27, wherein said passivation layer comprises a topmost nitride layer of said electronic component.

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40. (currently amended) The ~~electronic~~ circuitry component of Claim 27 further comprising a bump over said first portion.

20 41. (currently amended) The ~~electronic~~ circuitry component of Claim 40, wherein said bump comprises solder.

42. (currently amended) The ~~electronic~~ circuitry component of Claim 40 further comprising a copper layer between said bump and said first portion.

25 43. (currently amended) The ~~electronic~~ circuitry component of Claim 40, wherein said bump comprises a lead-free alloy.

44. (currently amended) The ~~electronic~~ circuitry component of Claim 27 further comprising a wirebonded wire bonded over said second portion.

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Claim 45 (canceled)

46. (currently amended) ~~An electronic~~ A circuitry component comprising:
a semiconductor substrate;
a metallization structure over said semiconductor substrate;
a passivation layer over said over said metallization structure, wherein an opening
5 in said passivation layer exposes a top surface of said metallization structure; and
a patterned circuit layer connected to said top surface, wherein said patterned
circuit layer comprises a first portion used to be wirebonded thereto and a second
portion used to be tested thereto.
- 10 47. (currently amended) The ~~electronic~~ circuitry component of Claim 46, wherein said
patterned circuit layer comprises gold.
48. (currently amended) The ~~electronic~~ circuitry component of Claim 46, wherein said
patterned circuit layer comprises a gold layer having a thickness greater than 1
15 micron.
49. (currently amended) The ~~electronic~~ circuitry component of Claim 46, wherein said
patterned circuit layer comprises copper.
- 20 50. (currently amended) The ~~electronic~~ circuitry component of Claim 46, wherein said
patterned circuit layer comprises nickel.